

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







10



HMC630LP3 / 630LP3E

v00.1007



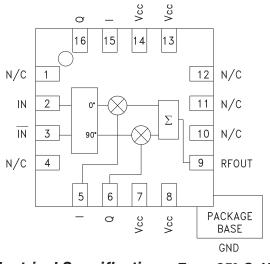
GaAs HBT VECTOR MODULATOR 700 - 1000 MHz

Typical Applications

The HMC630LP3(E) is ideal for:

- Wireless Infrastructure HPA & MCPA Error Correction
- Pre-Distortion or Feed-Forward Linearization
- Cellular / 3G Systems
- Beam Forming or RF Cancellation Circuits

Functional Diagram



Features

Continuous Phase Control: 360° Continuous Gain Control: 40 dB Low Output Noise Floor: -162 dBm/Hz

High Input IP3: +34 dBm

16 Lead 3x3mm SMT Package: 9mm²

General Description

The HMC630LP3 & HMC630LP3E are high dynamic range Vector Modulator RFICs which are targeted for RF predistortion and feed-forward cancellation circuits, as well as RF beam forming and amplitude/phase correction circuits. The I & Q ports of the HMC630LP3(E) can be used to continuously vary the phase and amplitude of RF signals by up to 360 degrees and 40 dB respectively, while supporting a 3 dB modulation bandwidth of 180 MHz. With an output IP3 of +24.5 dBm and output noise floor of -162 dBm/Hz (at maximum gain setting), the output IP3/noise floor ratio is 186.5 dB.

Electrical Specifications, $T_A = +25^{\circ}$ C, Vcc= +8V

Parameter	Min.	Тур.	Max.	Units
Frequency Range	0.7 - 1.0		GHz	
Maximum Gain ^[1]	-12	-10		dB
Gain Variation Over Temperature		0.02	0.03	dB/°C
Gain Flatness Across Any 60 MHz Bandwidth		0.10		dB
Gain Range		40		dB
Input Return Loss		15		dB
Output Return Loss		17		dB
Input Power for 1dB Compression (P1dB)	14	17		dBm
Input Third Order Intercept (IP3)		34		dBm
Output Noise		-162		dBm/Hz
Control Port Bandwidth (-3 dB)		180		MHz
Control Port Impedance		1.45k		Ohms
Control Port Capacitance		0.22		pF
Control Voltage Range	+0.5 to +2.5		Vdc	
Group Delay Variation Over 60 MHz Bandwidth		20		ps
Supply Current (Icq)		92		mA

Unless otherwise noted, measurements are made @ max. gain setting and 45° phase setting.

See application circuit for details.

^[1]Includes loss of input balun (0.75 dB typ.).

HMC630* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS -

View a parametric search of comparable parts.

EVALUATION KITS

· HMC630LP3 Evaluation Board

DOCUMENTATION

Data Sheet

· HMC630 Data Sheet

REFERENCE MATERIALS -

Quality Documentation

- Package/Assembly Qualification Test Report: 16L 3x3mm QFN Package (QTR: 11003 REV: 02)
- Package/Assembly Qualification Test Report: LP2, LP2C, LP3, LP3B, LP3C, LP3D, LP3F, LP3G (QTR: 2014-0364)
- Semiconductor Qualification Test Report: GaAs HBT-A (QTR: 2013-00228)

DESIGN RESOURCES 🖵

- HMC630 Material Declaration
- PCN-PDN Information
- · Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all HMC630 EngineerZone Discussions.

SAMPLE AND BUY 🖵

Visit the product page to see pricing options.

TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK 🖳

Submit feedback for this data sheet.

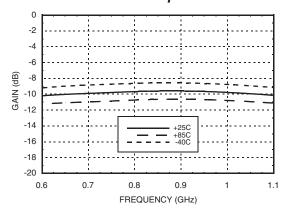
This page is dynamically generated by Analog Devices, Inc., and inserted into this data sheet. A dynamic change to the content on this page will not trigger a change to either the revision number or the content of the product data sheet. This dynamic page may be frequently modified.



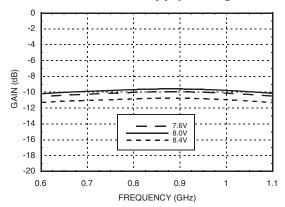


GaAs HBT VECTOR MODULATOR 700 - 1000 MHz

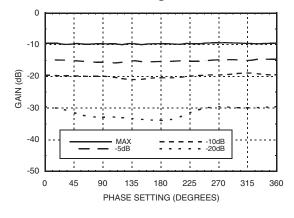
Maximum Gain vs. Temperature



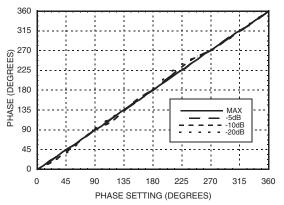
Maximum Gain vs. Supply Voltage



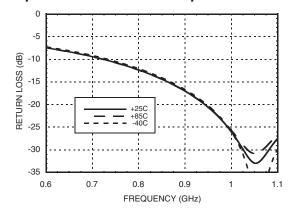
Gain vs. Phase Settings @ F= 900 MHz



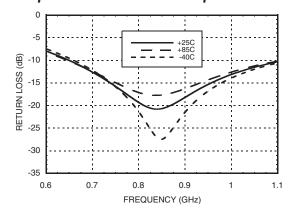
Phase vs. Phase Settings @ F= 900 MHz vs. Various Gain Settings



Input Return Loss vs. Temperature



Output Return Loss vs. Temperature





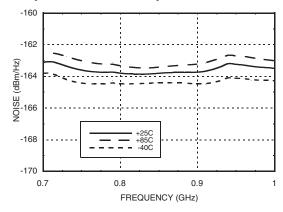
HMC630LP3 / 630LP3E

v00.1007

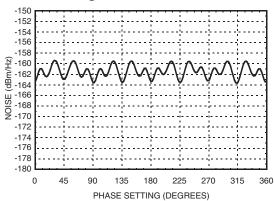


GaAs HBT VECTOR MODULATOR 700 - 1000 MHz

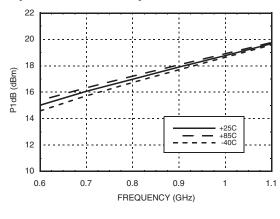
Output Noise vs. Temperature



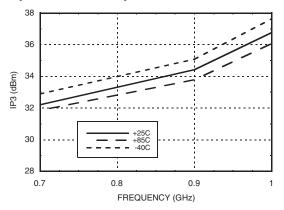
Output Noise vs. Phase Settings @ F= 900 MHz



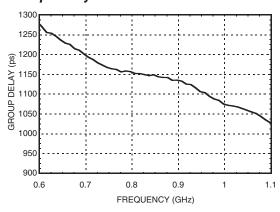
Input P1dB vs. Temperature



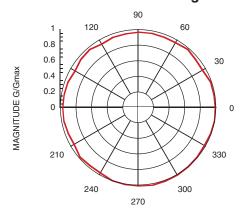
Input IP3 vs. Temperature



Group Delay



Linear Gain vs. Phase Setting







GaAs HBT VECTOR MODULATOR 700 - 1000 MHz

HMC630LP3 / 630LP3E

Typical Supply Current vs. Vcc

Vcc (V)	Icc (mA)
7.6	86
8.0	92
8.4	98

Note:

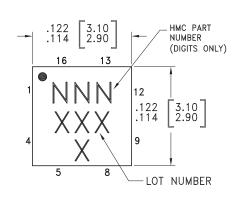
Modulator will operate over full voltage range shown above.

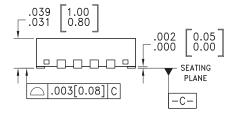


Absolute Maximum Ratings

RF Input (Vcc = +8V)	27 dBm
Supply Voltage (Vcc)	+10V
I & Q Input	-0.5V to +5.0V
Junction Temperature (Tc)	135 °C
Continuous Pdiss (T = 85°C) (Derate 34 mW/°C above 85°C)	1.7 W
Thermal Resistance (R _{th}) (junction to ground paddle)	29.6 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C

Outline Drawing





NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
- PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
 PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED PCB LAND PATTERN.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC630LP3	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	630 XXXX
HMC630LP3E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	630 XXXX

- [1] Max peak reflow temperature of 235 $^{\circ}\text{C}$
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX

HMC630LP3 / 630LP3E

v00.1007



GaAs HBT VECTOR MODULATOR 700 - 1000 MHz

Pin Description

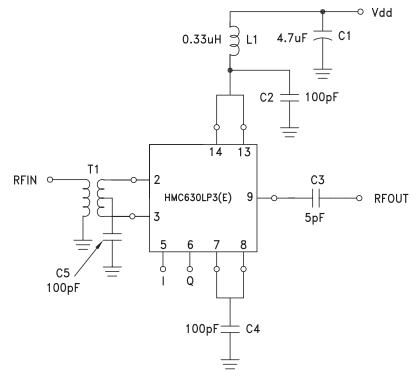
Pin Number	Function	Description	Interface Schematic
1, 4, 10 - 12	N/C	No connection. These pins may be connected to RF ground. Performance will not be affected	
2, 3	IN, ĪÑ	Differential RF inputs, 100 Ohms differential impedance. (i.e. each pin is 50 Ohms to ground). Must be DC blocked.	Vbias
5, 15	I	In-phase control input. Pins 5 and 15 are redundant. Either input can be used.	ο Vcc I,(Q)
6, 16	Q	Quadrature control input. Pins 6 and 16 are redundant. Either input can be used.	$5,(6)$ $1.88k\Omega$ $0.22pF$
7, 8, 13, 14	Vcc	Supply Voltage, pins are DC connected on-chip. It is only necessary to supply Vcc to any 1 of the 4 pins, but all 4 pins must be bypassed to ground. (See application circuit).	
9	RFOUT	RF Output: Must be DC blocked.	QVcc RFOUT
	GND	Ground: Backside of package has exposed metal ground paddle which must be connected to RF/DC ground.	O GND =





GaAs HBT VECTOR MODULATOR 700 - 1000 MHz

Application Circuit



* Pins 15 & 16 are redundant I & Q inputs.

Gain and Phase control are applied through the I and Q control ports. For a given linear gain (G) and phase (θ) setting, the voltages applied to these ports in all measurements are calculated as follows:

$$I(G,\theta) = Vmi + 1.0V \frac{G}{G \max} Cos(\theta)$$
$$Q(G,\theta) = Vmq + 1.0V \frac{G}{G \max} Sin(\theta)$$

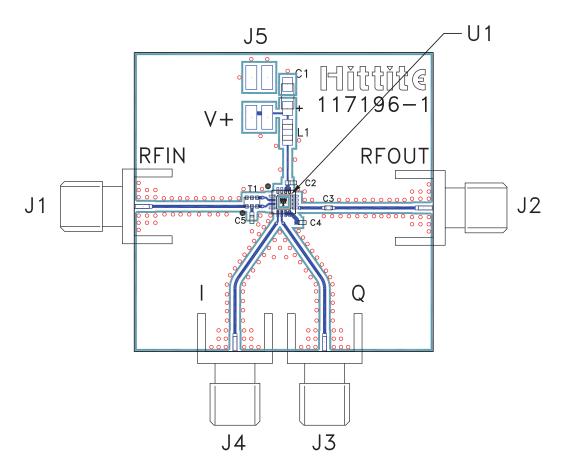
Where Vmi and Vmq are the I and Q voltage settings corresponding to maximum isolation at room temperature and F = 0.9 GHz. Note that $G=10^x$ and $G=10^x$ and





GaAs HBT VECTOR MODULATOR 700 - 1000 MHz

Evaluation PCB



List of Materials for Evaluation PCB 117198 [1]

Item	Description
J1 - J4	PCB Mount SMA Connector
J5	2 mm DC Header
C1	4.7 μF Capacitor, Tantalum
C2, C4, C5	100 pF Capacitor, 0402 Pkg.
C3 [3]	5 pF Capacitor, 0402 pkg
T1	Balun, 0805 Pkg. ANAREN BD0810J50100A
L1	330 nH Inductor, 0805 Pkg.
U1	HMC630LP3(E) Vector Modulator
PCB [2]	117196 Evaluation PCB

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350, Er = 3.48

[3] Locate close to HMC630LP3E package

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.



HMC630LP3 / 630LP3E

v00.1007



Notes:

GaAs HBT VECTOR MODULATOR 700 - 1000 MHz